Code No: **RT41041**

Set No. 1

IV B.Tech I Semester Regular/Supplementary Examinations, Oct/Nov - 2018 VLSI DESIGN

(Common to Electronics and Communication Engineering and Electronics and Instrumentation Engineering)

Time: 3 hours Max. Marks: 70 Question paper consists of Part-A and Part-B Answer ALL sub questions from Part-A Answer any THREE questions from Part-B **** PART–A (22 Marks) 1. a) Compare CMOS, Bipolor, BiCMOS technologies? [4] Write a note on the general observation about design rules. b) [3] Explain the criteria for choice of layers. [4] c) Draw the typical architecture of PLA. [3] Write a short note on SoC Design. e) [4] List the applications of FPGA. f) [4] PART-B (3x16 = 48 Marks)What are the steps involved in the nMOS fabrication? Explain with neat 2. a) sketches. [8] Derive the relationship between drain to source current I_{ds} verses drain to source voltage V_{ds} in non-saturated and saturated region. [8] What is a stick diagram? Draw the stick diagram and layout for a CMOS 3. a) [8] inverter. b) Explain about double poly CMOS rules. [8] 4. Explain the concept of sheet resistance and apply it to compute the ON resistance a) (VDD to GND) of an NMOS inverter having pull up to pull down ratio of 4:1, If n channel resistance is Rsn = 104Ω per square. [8] b) What is inverter delay? How delay is calculated to for multiple stages? [8] Explain switch logic and its arrangements? And also explain properties of 5. a) transmission gate. [8] Discuss the general arrangement of a 4-bit arithmetic process. b) [8] Explain the importance of package selection. [8] 6. a) Explain the importance of design for testability. b) [8] Explain about building block architecture of FPGA. 7. a) [8] b) Explain the design flow using FPGA. [8]

Code No: **RT41041**

Set No. 2

IV B.Tech I Semester Regular/Supplementary Examinations, Oct/Nov - 2018 **VLSI DESIGN**

(Common to Electronics and Communication Engineering and Electronics and **Instrumentation Engineering**)

Time: 3 hours Max. Marks: 70 Question paper consists of Part-A and Part-B Answer ALL sub questions from Part-A Answer any THREE questions from Part-B **** PART–A (22 Marks) Define threshold voltage of a MOS device and explain its significance. 1. a) [4] Explain how stick diagrams can be used for layout diagrams. [3] b) Write short notes on area capacitances of layers. [4] c) d) Explain a four line Gray code to Binary code converter. [4] Write a short note on mixed signal design. e) [3] List out the steps in FPGA design flow. f) [4] PART-B (3x16 = 48 Marks)Explain the processing steps used in IC fabrication process. 2. [8] Derive the expression for the ratio between Zp.u and Zp.d if an nMOS inverter is to be driven from another nMOS inverter. [8] Design a stick diagram for inverter using CMOS. 3. a) [8] Design a layout diagram for CMOS 3-input NAND gate. [8] Explain scaling of MOS circuits. Give merits and demerits of scaling. 4. a) [8] Describe three sources of wiring capacitances. Explain the effect of wiring capacitance on the performance of a VLSI circuit. [8] 5. a) Discuss about Two-phase clocking in detail. [8] With an example, Explain about system design. b) [8] Discuss the VLSI design issues and design trends. 6. a) [8] b) Explain the ASIC design flow. [8] Write the VHDL code to implement stack. 7. a) [8] b) Explain the architectural features of FPGA. [8]

Code No: **RT41041 R**

Time: 3 hours

Set No. 3

Max. Marks: 70

[8]

IV B.Tech I Semester Regular/Supplementary Examinations, Oct/Nov - 2018 VLSI DESIGN

(Common to Electronics and Communication Engineering and Electronics and Instrumentation Engineering)

Question paper consists of Part-A and Part-B Answer ALL sub questions from Part-A Answer any THREE questions from Part-B PART-A (22 Marks) 1. a) Define the terms SSI, MSI, LSI and $\overline{\text{VLSI}}$. [4] b) Define stick diagram and layout diagram. [3] Draw and explain fan-in and fan-out characteristics of CMOS design. [3] c) Write short notes on switch logic and its arrangements. d) [4] Draw the ASIC design flow. e) [4] Explain the functions of LUT based logic block. f) [4] PART-B (3x16 = 48 Marks)With neat sketches explain BICMOS fabrication in an n-well process. 2. a) [8] Explain and derive the expressions for MOS transistor parameters g_m , g_{ds} and ω_0 . b) [8] Design a layout for CMOS 2-input NOR gate. 3. a) [8] Write a short note on 2µm Double Metal, Double Poly, CMOS/BiCMOS rules. b) [8] Explain constituents of wiring capacitance. [8] 4. a) What are the limits on logic levels and supply voltage due to noise in scaling? [8] 5. a) Explain bus arbitration logic for n-line bus structured design approach. [8] Realize the 2-i/p NOR gate using NMOS, PMOS and CMOS technologies. b) [8] Discuss about design for testability in VLSI design. [8] 6. a) b) Draw and explain the FPGA design flow. [8] 7. a) Explain implementation of queue using VHDL [8]

b) Write the VHDL code to implement four bit shift register.

Code No: RT41041

Set No. 4

IV B.Tech I Semester Regular/Supplementary Examinations, Oct/Nov - 2018 VLSI DESIGN

(Common to Electronics and Communication Engineering and Electronics and Instrumentation Engineering)

Time: 3 hours Max. Marks: 70 Question paper consists of Part-A and Part-B Answer ALL sub questions from Part-A Answer any THREE questions from Part-B **** PART-A (22 Marks) 1. a) Explain the Latch-up effect in CMOS circuits with suitable diagrams. [4] b) Draw the circuit diagram for CMOS two-input NOR gate. [3] Write short notes on realization of gates using CMOS technology. [4] c) d) Explain a four-bit dynamic shift register. [4] List out the steps in FPGA design flow. e) [3] Write about configuration modes. f) [4] PART-B (3x16 = 48 Marks)Explain the structures of n MOS enhancement mode, depletion mode and p-MOS 2. enhancement mode transistors. [8] b) Draw and explain the operation of BiCMOS inverter. [8] What is a stick diagram and explain about different symbols used for components 3. a) in stick diagram. [8] b) Design a stick diagram and layout for the CMOS logic shown below. $Y = \overline{(AB) + (CD)}$ [8] Realize basic gates using NMOS. 4. a) [8] Explain scaling factors for device parameters. [8] 5. a) Explain the structured design approach of parity generator. [8] Explain the design of a 4-bit shifter. [8] a) Explain the stuck at fault model with example. [8] b) Explain about the clocking mechanism. [8] 7. a) Explain the FPGA design process. [8] b) Explain the concept of sheet resistance. [8]